Unit: mm

TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSVI)

2SK3935

Switching Regulator Applications

• Low drain-source ON resistance : $RDS(ON) = 0.18\Omega$ (typ.)

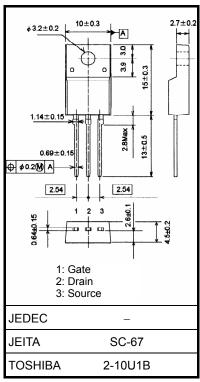
• High forward transfer admittance $: |Y_{fs}| = 10 \text{ S (typ.)}$ • Low leakage current $: I_{DSS} = 100 \mu\text{A (max) (V}_{DS} = 450 \text{ V)}$

• Enhancement model : $V_{th} = 2.0 \text{ to } 4.0 \text{ V}$

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	450	V	
Drain-gate voltage (R_{GS} = 20 k Ω)		V_{DGR}	450	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	ID	17	Α	
	Pulse(Note 1)	I _{DP}	68	Α	
Drain power dissipation	1	P _D	50	W	
Single pulse avalanche energy (Note 2)		E _{AS}	918	mJ	
Avalanche current		I _{AR}	17	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

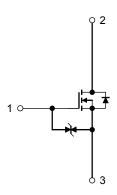
Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 5.3 mH, R_G = 25 Ω , I_{AR} = 17 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device. Handle with care.





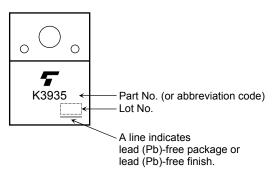
Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain-source bre	eakdown voltage	V (BR) GSS	I_{G} = ±10 μ A, V_{GS} = 0 V	±30	_	_	V
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 450 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source bre	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	450	_	1	V
Gate threshold v	/oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	N resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 8.5 A	_	0.18	0.25	Ω
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 8.5 A	2.5	9.5	_	S
Input capacitano	ce	C _{iss}		_	3100	_	pF
Reverse transfe	r capacitance	C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	20	_	
Output capacitance		Coss		_	270	_	
Switching time	Rise time	t _r	V _{DD} ≈ 200 V	_	70	_	
	Turn-on time	t _{on}		_	130	_	ns ns
	Fall time	t _f		_	70	_	
	Turn-off time	t _{off}	Duty ≤ 1%, t _w = 10 μs		280	-	
Total gate charge (gate-source plus gate-drain)		Qg	V _{DD} ≈ 360 V, V _{GS} = 10 V, I _D = 17 A	_	62		nC
Gate-source charge		Q _{gs}		_	40	_	
Gate-drain ("Miller") charge		Q _{gd}		_	22	_	

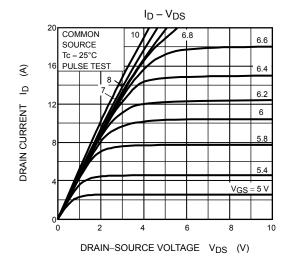
Source-Drain Ratings and Characteristics (Ta = 25°C)

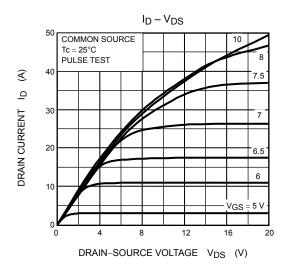
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	17	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	68	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 17 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 17 A, V _{GS} = 0 V	_	1400		ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 100 A / μS	_	21	_	μС

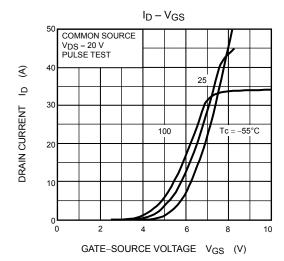
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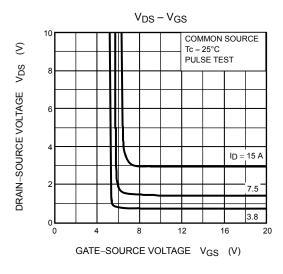


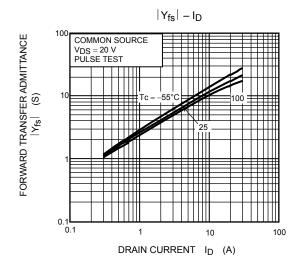
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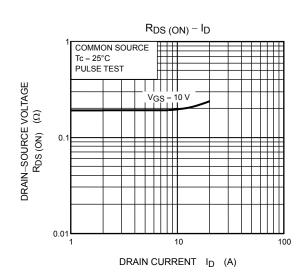


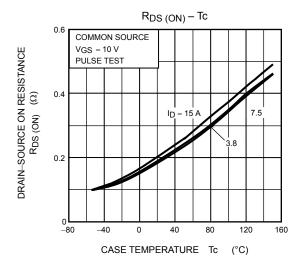


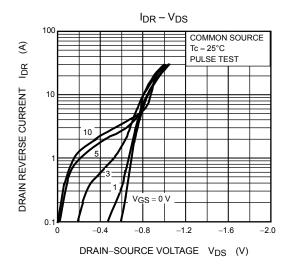


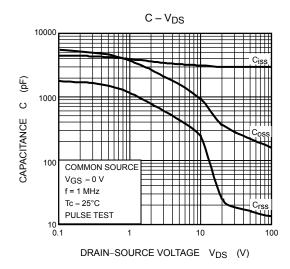


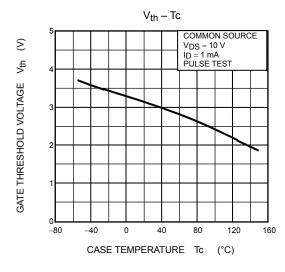


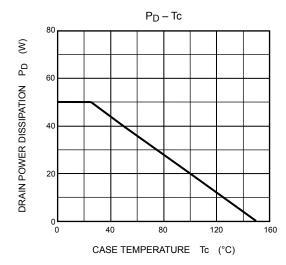


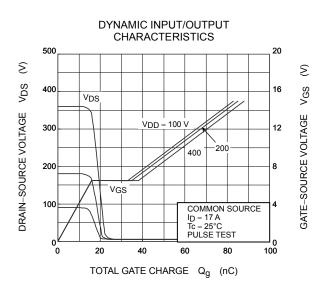


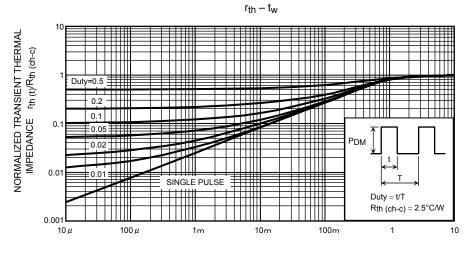




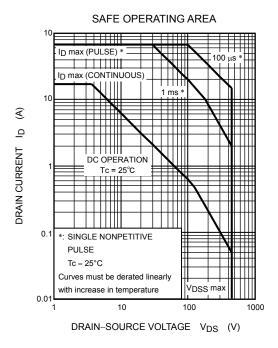


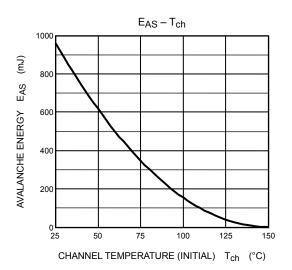


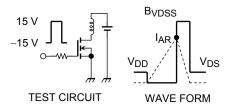




PULSE WIDTH tw (s)







$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 5.3~mH \end{aligned}$$

$$EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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